

Title (en)
COMPOSITES HAVING AN INTERMETALLIC CONTAINING MATRIX

Publication
EP 0253497 A3 19891108 (EN)

Application
EP 87305181 A 19870611

Priority
US 87389086 A 19860613

Abstract (en)
[origin: EP0253497A2] This invention relates to a composite material comprising an in-situ precipitated second phase in an intermetallic matrix, and to the process for making such a composite.

IPC 1-7
C22C 1/10; **C22C 1/05**; **C04B 35/65**

IPC 8 full level
B22F 3/23 (2006.01); **B22F 9/14** (2006.01); **B23K 35/32** (2006.01); **B23K 35/40** (2006.01); **C04B 35/58** (2006.01); **C04B 35/65** (2006.01); **C22C 1/05** (2006.01); **C22C 1/10** (2006.01); **C22C 29/00** (2006.01); **C22C 32/00** (2006.01); **C22C 47/08** (2006.01); **C22C 49/00** (2006.01); **C22C 49/14** (2006.01)

CPC (source: EP US)
B22F 3/23 (2013.01 - EP US); **B22F 9/14** (2013.01 - EP US); **B23K 35/327** (2013.01 - EP US); **B23K 35/40** (2013.01 - EP US); **B82Y 30/00** (2013.01 - EP US); **C04B 35/65** (2013.01 - EP US); **C22C 1/058** (2023.01 - EP US); **C22C 1/10** (2013.01 - EP US); **C22C 1/1015** (2013.01 - EP US); **C22C 1/1036** (2013.01 - EP US); **C22C 1/1047** (2023.01 - EP); **C22C 1/1052** (2023.01 - EP); **C22C 1/1068** (2013.01 - EP US); **C22C 29/00** (2013.01 - EP US); **C22C 32/00** (2013.01 - EP US); **C22C 32/0078** (2013.01 - EP US); **C22C 47/06** (2013.01 - EP US); **C22C 47/08** (2013.01 - EP US); **C22C 49/00** (2013.01 - EP US); **C22C 49/14** (2013.01 - EP US); **C22C 1/1047** (2023.01 - US); **C22C 1/1052** (2023.01 - US)

Citation (search report)

- [Y] EP 0165707 A2 19851227 - SUMITOMO ELECTRIC INDUSTRIES [JP], et al
- [Y] FR 2105986 A5 19720428 - WALL COLMONOY CORP
- [A] EP 0110268 A2 19840613 - GEN ELECTRIC [US]
- [A] EP 0115688 A2 19840815 - CORNING GLASS WORKS [US]
- [A] DE 2102777 A1 19720803 - NICKL J, et al
- [A] ZEITSCHRIFT FÜR METALLKUNDE, vol. 68, no. 4, April 1977, pages 241-251; H. SPRENGER et al.: "Boride und Silizide als Verstärkungsphasen in eutektischen Hochtemperaturwerkstoffen"

Cited by
US6025065A; DE102008051042A1; CN110723974A; US6022505A; CN113025405A; US6271162B1; US6818315B2; WO9837034A1; WO9620902A1; WO8807593A3; WO02053316A1; EP0378504B1

Designated contracting state (EPC)
DE FR GB IT SE

DOCDB simple family (publication)
EP 0253497 A2 19880120; **EP 0253497 A3 19891108**; **EP 0253497 B1 19940817**; CA 1304962 C 19920714; DE 3750385 D1 19940922; DE 3750385 T2 19941201; JP 3069354 B2 20000724; JP S63307231 A 19881214; US 4774052 A 19880927

DOCDB simple family (application)
EP 87305181 A 19870611; CA 538525 A 19870601; DE 3750385 T 19870611; JP 13481587 A 19870529; US 87389086 A 19860613